

Vishay General Semiconductor

# SMD Photovoltaic Solar Cell Protection Schottky Rectifier



TO-277A (SMPC)

Cathode O Anode 1

PRIMARY CHARACTERISTICS				
I <sub>F(AV)</sub>	15 A			
V <sub>RRM</sub>	30 V			
I <sub>FSM</sub>	280 A			
E <sub>AS</sub>	20 mJ			
V <sub>F</sub> at I <sub>F</sub> = 15 A	0.42 V			
T <sub>J</sub> max.	150 °C			

For use in solar cell junction box as a bypass diode for protection, using DC forward current without reverse bias.

**TYPICAL APPLICATIONS** 

## FEATURES

- Very low profile typical height of 1.1 mm
- Ideal for automated placement
- Guardring for overvoltage protection
- Low forward voltage drop, low power losses
- High efficiency
- Low thermal resistance
- Meets MSL level 1, per J-STD-020, LF maximum peak of 260 °C
- Compliant to RoHS Directive 2002/95/EC and in accordance to WEEE 2002/96/EC
- Halogen-free according to IEC 61249-2-21 definition

### **MECHANICAL DATA**

**Case:** TO-277A (SMPC) Molding compound meets UL 94 V-0 flammability rating Base P/N-M3 - halogen-free, RoHS compliant, and commercial grade

**Terminals:** Matte tin plated leads, solderable per J-STD-002 and JESD 22-B102

M3 suffix meets JESD 201 class 1A whisker test

<b>MAXIMUM RATINGS</b> (T <sub>A</sub> = 25 °C unless otherwise noted)					
PARAMETER		SS15P3S	UNIT		
Device marking code		153S			
Maximum repetitive peak reverse voltage	V <sub>RRM</sub>	30	V		
Maximum DC forward current (fig. 1)	I <sub>F</sub>	15 <sup>(1)</sup> 4.5 <sup>(2)</sup>	А		
Peak forward surge current 10 ms single half sine-wave superimposed on rated load	I <sub>FSM</sub>	280	A		
Non-repetitive avalanche energy at $I_{AS}$ = 2.0 A, $T_{J}$ = 25 $^{\circ}\text{C}$	E <sub>AS</sub>	20	mJ		
Operating junction and storage temperature range	T <sub>OP</sub> , T <sub>STG</sub>	- 55 to + 150	°C		
Junction temperature in DC forward current without reverse bias, t $\leq$ 1 h $^{(3)}$	TJ	≤ 200	°C		

Notes

<sup>(1)</sup> Mounted on 30 mm x 30 mm AI PCB with 50 mm x 25 mm x 100 mm fin heat sink

<sup>(2)</sup> Free air, mounted on recommended copper pad area

<sup>(3)</sup> Meets the requirements of IEC 61215 Ed. 2 bypass diode thermal test

RoHS COMPLIANT HALOGEN

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# SS15P3S



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<b>ELECTRICAL CHARACTERISTICS</b> ( $T_A = 25 \text{ °C}$ unless otherwise noted)						
PARAMETER	TEST CONDITIONS		SYMBOL	TYP.	MAX.	UNIT
Instantaneous forward voltage	l <sub>F</sub> = 7.5 A	– T <sub>A</sub> = 25 °C	V <sub>F</sub> <sup>(1)</sup>	0.43	-	V
	I <sub>F</sub> = 15 A			0.50	0.57	
	I <sub>F</sub> = 7.5 A	– T <sub>A</sub> = 125 °C		0.32	-	
	I <sub>F</sub> = 15 A			0.42	0.49	
Reverse current	V 20.V	T <sub>A</sub> = 25 °C	I <sub>B</sub> <sup>(2)</sup>	150	1000	μA
	V <sub>R</sub> = 30 V T <sub>A</sub> = 125 °C	IR (=/	59	120	mA	
Typical junction capacitance	4.0 V, 1 MHz		CJ	930	-	pF

#### Notes

 $^{(1)}$  Pulse test: 300  $\mu s$  pulse width, 1 % duty cycle

 $^{(2)}$  Pulse test: Pulse width  $\leq 40\ ms$ 

<b>THERMAL CHARACTERISTICS</b> (T <sub>A</sub> = 25 °C unless otherwise noted)					
PARAMETER	SYMBOL	VALUE	UNIT		
Typical thermal resistance	$R_{ ext{ heta}JA}$ (1)	100	°C/W		
	R <sub>0JM</sub> <sup>(2)</sup>	3	0/00		

#### Notes

<sup>(1)</sup> Free air, mounted on recommended copper pad area. Thermal resistance  $R_{\theta JA}$  - junction to ambient.

 $^{(2)}$  Mounted on 30 mm x 30 mm AI PCB with 50 mm x 25 mm x 100 mm fin heat sink. Thermal resistance  $R_{\theta JM}$  - junction to mount.

ORDERING INFORMATION (Example)					
PREFERRED P/N	UNIT WEIGHT (g)	PREFERRED PACKAGE CODE	BASE QUANTITY	DELIVERY MODE	
SS15P3S-M3/86A	0.10	86A	1500	7" diameter plastic tape and reel	
SS15P3S-M3/87A	0.10	87A	6500	13" diameter plastic tape and reel	

### **RATINGS AND CHARACTERISTICS CURVES**

(T<sub>A</sub> = 25 °C unless otherwise noted)

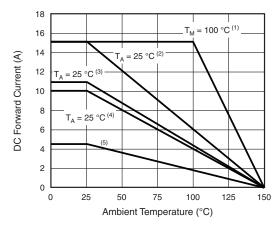


Fig. 1 - Maximum Current Derating Curve

#### Notes

- $^{(1)}$  Mounted on 30 mm x 30 mm Al PCB with 50 mm x 25 mm x 100 mm fin heat sink,  $T_{\rm M}$  measured at the terminal of cathode band
- <sup>(2)</sup> Mounted on 30 mm x 30 mm AI PCB ( $R_{\theta JA} = 20 \text{ °C/W}$ )
- $^{(3)}$  Mounted on 30 mm x 30 mm x 2 copper pad areas FR4 PCB (R<sub> $\theta$ JA</sub> = 30 °C/W)
- <sup>(4)</sup> Mounted on 25 mm x 25 mm x 2 copper pad areas FR4 PCB ( $R_{\theta JA} = 30 \text{ °C/W}$ )
- <sup>(5)</sup> Free air, mounted on recommended copper pad area  $(R_{\theta,JA} = 100 \text{ °C/W})$

For technical questions within your region, please contact one of the following: DiodesAmericas@vishay.com, DiodesAsia@vishay.com, DiodesEurope@vishay.com Document Number: 89128 Revision: 13-May-11

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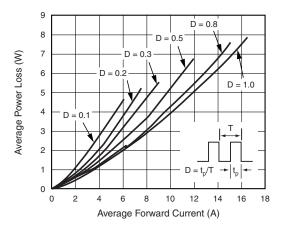


Fig. 2 - Forward Power Loss Characteristics

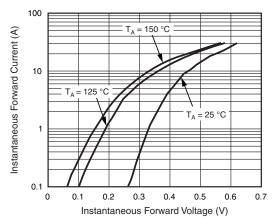


Fig. 3 - Typical Instantaneous Forward Characteristics

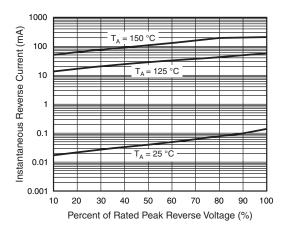


Fig. 4 - Typical Reverse Leakage Characteristics

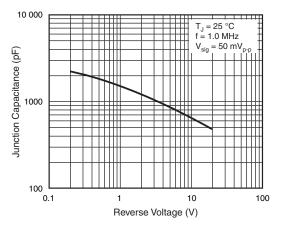


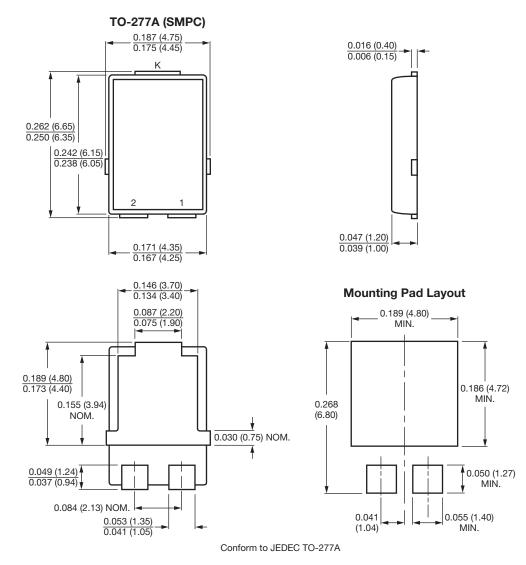
Fig. 5 - Typical Junction Capacitance

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## **PACKAGE OUTLINE DIMENSIONS** in inches (millimeters)



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